

[Upgrade to revision]
RX23W Group
BLE Module Firmware Integration Technology Rev.2.40

R20TS0865EJ0100
Rev.1.00
Jul. 01, 2022

Outline

RX23W Group BLE Module Firmware Integration Technology (FIT) has been updated from Rev.2.31 to Rev.2.40.

Since the *R_BLE_Open* API has been modified, please upgrade the revision if you are using this FIT module.

1. Products to Be Updated

RX23W Group BLE Module Firmware Integration Technology
Rev.1.00, 1.01, 1.10, 2.00, 2.10, 2.11, 2.20, 2.30, 2.31

2. Description

The main change is as follows. Refer to the Application Note's Revision History for other changes.

[RX23W Group BLE Module Firmware Integration Technology Application Note](#)

2.1 Issue Fixed

2.1.1 Adjustment of Initialization Stability Wait Time of *R_BLE_Open*

There was an issue that H/W initialization error occurred in the initialization process of the *R_BLE_Open* API depending on the conditions when power was applied, and the *r_ble_rf_control_error* function was called with *err_no* "0xFF04". As a modification of this issue, the stable waiting time of the initialization process in *R_BLE_Open* has been adjusted. This modification will increase the processing time of *R_BLE_Open* by about 200msec.

2.1.2 Stabilization of peripheral communication operation when Connection Latency is enabled

Fixed an issue when the RX23W is a peripheral role and the connection latency is non-zero, data transmission timing on the RX23W side rarely goes out of sync with the central device, causing a delay in data transmission until the RX23W resynchronization.

2.1.3 Fixed an issue the bonding information in the data flash cannot be deleted

Fixed an issue that the remaining bonding information cannot be deleted due to incorrect references to the bonding information in the data flash after using the *R_BLE_SECD_DelRemKeys* API with specified BD address to delete a bonding information set when two or more bonding information sets are registered.

3. Updating the Product

Download the FIT module using the RX Smart Configurator and update the software component version.
For details, visit the following web site and refer to the RX Smart Configurator User's Guide.

[Firmware Integration Technology \(FIT\) | Renesas](#)

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Jul.01.22	-	First edition issued

Renesas Electronics has used reasonable care in preparing the information included in this document, but Renesas Electronics does not warrant that such information is error free. Renesas Electronics assumes no liability whatsoever for any damages incurred by you resulting from errors in or omissions from the information included herein.

The past news contents have been based on information at the time of publication. Now changed or invalid information may be included.

The URLs in the Tool News also may be subject to change or become invalid without prior notice.

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,
Koto-ku, Tokyo 135-0061, Japan
www.renesas.com

Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation.

The *Bluetooth*® word mark and logos are registered trademarks owned by Bluetooth SIG, Inc. and any use of such marks by Renesas Electronics Corporation is under license. All trademarks and registered trademarks are the property of their respective owners.

Contact information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit:
www.renesas.com/contact/